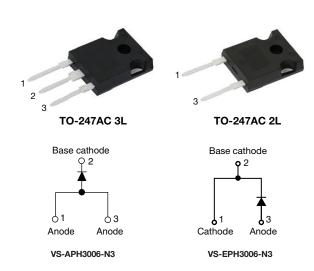


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Vishay Semiconductors

# Hyperfast Rectifier, 30 A FRED Pt®



PRIMARY CHARACTERISTICS						
I <sub>F(AV)</sub>	30 A					
$V_{R}$	600 V					
V <sub>F</sub> at I <sub>F</sub>	1.4 V					
t <sub>rr</sub> typ.	27 ns					
T <sub>J</sub> max.	175 °C					
Package	TO-247AC 3L, TO-247AC 2L					
Circuit configuration	Single					

#### **FEATURES**

- · Low forward voltage drop
- Hyperfast soft recovery time
- 175 °C operating junction temperature
- Designed and qualified according to JEDEC®-JESD 47





### **DESCRIPTION / APPLICATIONS**

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	$V_{RRM}$		600	V			
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 112 °C	30	۸			
Non-repetitive peak surge current	I <sub>FSM</sub>	$T_C = 25  ^{\circ}\text{C},  t_p = 10  \text{ms}$	220	A			
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C			

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	600	-	-			
Face and continue	V <sub>F</sub>	I <sub>F</sub> = 30 A	-	2.0	2.65			
Forward voltage		I <sub>F</sub> = 30 A, T <sub>J</sub> = 150 °C	-	1.4	1.8			
Reverse leakage current	I <sub>R</sub>	$V_R = V_R$ rated	-	-	30			
neverse leakage current		$T_J = 150 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	=	300	μA		
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	20	-	pF		
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8.0	-	nH		



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST (	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1 A, dI_F/dt = 50$	0 A/μs, V <sub>R</sub> = 30 V	-	26	35			
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	26	-	ns		
		T <sub>J</sub> = 125 °C	$I_F = 30 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	70	-			
Dook room ourrent	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	3.5	-	А		
Peak recovery current		T <sub>J</sub> = 125 °C		-	7.6	-			
Daviere received the same	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	50	=	200		
Reverse recovery charge		T <sub>J</sub> = 125 °C		-	280	-	nC		

THERMAL - MECHANI	THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C			
Thermal resistance, junction to case	$R_{thJC}$		ı	0.7	1.1	°C/W			
Thermal resistance, junction to ambient per leg	$R_{\text{thJA}}$	Typical socket mount	ı	-	40				
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth, and greased	-	0.5	-				
Weight			-	5.5	-	g			
vveignt			-	0.2	-	oz.			
Mounting torque			1.2 (10)	-	2.4 (20)	kgf · cm (lbf · in)			
Maulina desire		Case style TO-247AC 3L	APH3006			•			
Marking device		Case style TO-247AC 2L	EPH3006						

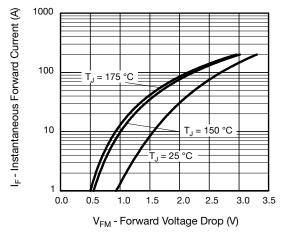


Fig. 1 - Typical Forward Voltage Drop Characteristics

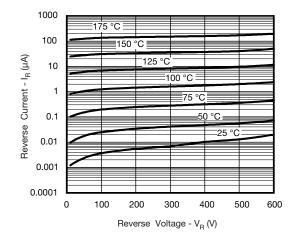


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

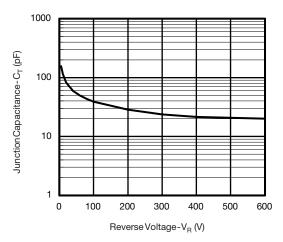


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

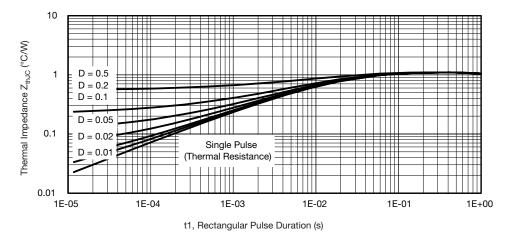


Fig. 4 - Max. Thermal Impedance Z<sub>thJC</sub> Characteristics

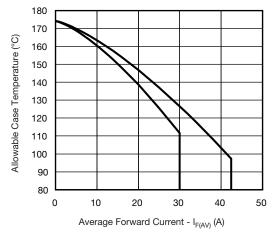


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

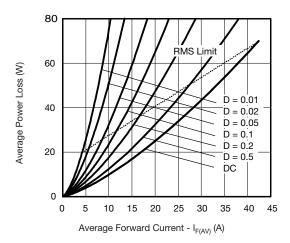


Fig. 6 - Forward Power Loss Characteristics

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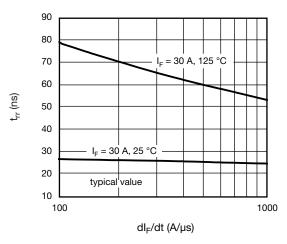


Fig. 7 - Typical Reverse Recovery vs. dl<sub>F</sub>/dt

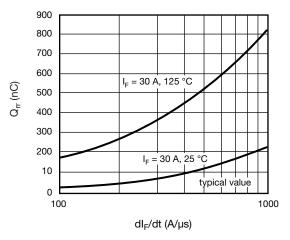
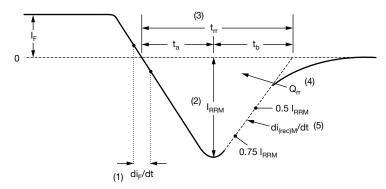


Fig. 8 - Typical Stored Charge vs. dl<sub>E</sub>/dt



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75 I<sub>RRM</sub> and 0.50 I<sub>RRM</sub> extrapolated to zero current.
- (4)  ${\rm Q_{rr}}$  area under curve defined by  ${\rm t_{rr}}$  and  ${\rm I_{RRM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

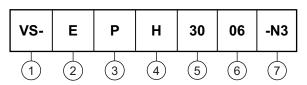
Fig. 9 - Reverse Recovery Waveform and Definitions

# VS-APH3006-N3, VS-EPH3006-N3

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### **ORDERING INFORMATION TABLE**

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration

• E = single diode, 2 pins

• A = single diode, 3 pins

**3** - P = TO-247AC

4 - H = hyperfast recovery time

5 - Current code (30 = 30 A)

6 - Voltage code (06 = 600 V)

7 - Environmental digit:

-N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

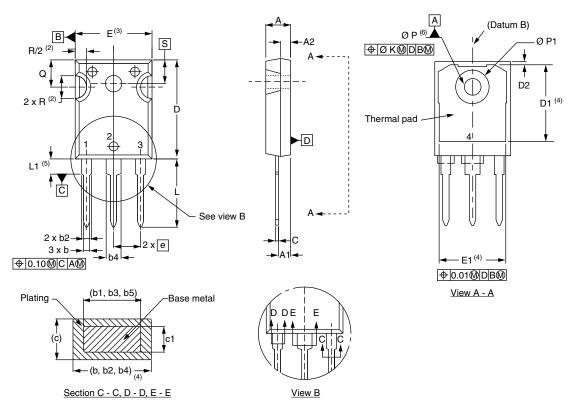
ORDERING INFORMATION (Example)						
PREFERRED P/N QUANTITY PER TUBE MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION						
VS-APH3006-N3	25	500	Antistatic plastic tube			
VS-EPH3006-N3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS				
Dimensions	TO-247AC 3L	www.vishay.com/doc?96138		
Dimensions	TO-247AC 2L	www.vishay.com/doc?96144		
Part marking information	TO-247AC 3L	www.vishay.com/doc?95007		
Part marking information	TO-247AC 2L	www.vishay.com/doc?95442		
SPICE model		www.vishay.com/doc?96580		



### **TO-247AC 3L**

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INCHES		NOTES
STIVIDUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.17	1.37	0.046	0.054	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	IROL MILLIMETERS INCHES		NOTES		
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.35	0.020	0.053	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46	BSC	0.215	BSC	
ØK	0.2	254	0.0	0.010	
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		

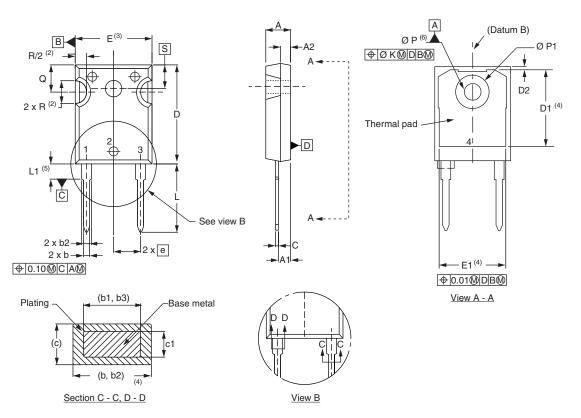
#### **Notes**

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension Q



### **TO-247AC 2L**

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES	T
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
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b3	1.65	2.34	0.065	0.092		
С	0.38	0.89	0.015	0.035		
c1	0.38	0.84	0.015	0.033		
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